2026 OFC *First News*

Each year, OFC unites industry leaders, academia and government representatives from more than 90 countries across the globe, to participate in a comprehensive technical program and a sold-out exhibition showcasing the latest innovations driving the optical communication field forward.

With over 16,000 expected registrants and an exhibit hall packed with more than 700 exhibitors, OFC 2026 is an unparalleled gathering for industry professionals and the global hub for innovation and collaboration.

Topics such as 224G SerDes and 1.6T links, AI, smart infrastructure monitoring enabled by advanced fiber optics and the latest in CPO, multicore fiber, data center technology and quantum networking will capture the interest of our global audience facilitating the exploration of the latest advancements in optical communications and networking technology.

We invite you to get a sneak peek at some of the news that our exhibitors will be sharing at the conference.

1Finity

Booth 1949
Release Date: 03/02/2026
Category: Communications Equipment

Introducing the Ultra Optical System L1000/L2000 Open Lined System (OLS) platform. This open, performance-optimized platform provides both core optical infrastructure for hyperscalers and cloud providers, and enables service providers to offer high-capacity managed optical services. The

L1000/2000 is purpose-built with an optimized Direct Attach architecture for high-capacity transmission and rapid scaling while reducing power and space. Available in various size and power options, it offers flexibility for any operating environment. This system guarantees 800G+ speeds, lowering Total Cost of Ownership (TCO). Its future-proof design includes Multi-Rail transmission support, ensuring even greater long-term power and space efficiency.

Contact: Ally Heddaeus 214-717-3105, ally.heddaeus@fujitsu.com, www.1finity.com

3SAE Technologies, Inc.

Booth 5100
Release Date: 03/02/2026
Category: Integrated Photonics

3SAE Technologies is proud to present the OctaPod® Fast Alignment Micro-Robot at OFC, the premier solution for scalable photonic production. Based on the 6-DOF PentaPod® parallel kinematic design, OctaPod delivers sub-micron resolution with industry-leading thermal stability and rigidity. Built-in algorithms enable fast optimization with <0.02dB reproducibility for multichannel devices. Engineered for 24/7 use, this compact, fanless system features an integrated controller, >20,000-hour MTBF, and field-repairability for seamless and cost-effective integration into manufacturing tooling. Discover how OctaPod's fast alignment and seamless integration streamline silicon photonics assembly at booth 5100 or contact info@3sae.com to discuss your application.

Contact: Don Grasso, 615-778-8812, info@3sae.com, www.3sae.com

Acacia

Meeting Room 303A-B
Release Date: 03/02/2026
Category: Pluggables

Acacia's broad portfolio of market leading coherent pluggables and performance optimized modules along with client optics components enable network operators to scale AI at the speed of light. As the pioneer of coherent pluggables, Acacia enables speeds from 100G to 1.2T, with the broadest field-proven portfolio of 400G coherent pluggables and the industry's first 800GZR+ with interop PCS to address the needs of network operators worldwide. Acacia's coherent modules are already being deployed in today's AI build outs while the company's expanded line of client optics components are delivering the higher-bandwidth, lower power and smaller footprint to meet the intra-data center optical interconnect demand.

Contact: Kelly Karr, 408-718-9350, kelly@karrpr.com, www.acacia-inc.com

Aehr Test Systems

Booth 5009
Release Date: 02/17/2026
Category: Laboratory & Test Equipment

Aehr secures key AI production burn-in win with initial order of Sonoma Systems for lead hyperscale customer's next-generation AI ASIC processors. Aehr Test Systems, a leading provider of test and burn-in solutions for semiconductor devices used in artificial intelligence (AI), data center, automotive, and industrial applications, today announced a key strategic win with an initial production purchase order from its lead production customer for package-level burn-in of the customer's next-generation, significantly higher-power AI processor used in data center training and inference applications.

Contact: Chris Jost, 408-859-2995, cjost@aehr.com, www.aehr.com

Aehr Test Systems

Booth 5009
Release Date: 02/17/2026
Category: Data Center Inter Connects

Aehr Test Systems has received a follow-on purchase order from its lead silicon photonics customer for production wafer-level test and burn-in of silicon photonics integrated circuits used in data center optical interconnects and emerging optical I/O architectures for AI processors. The order reflects expanding production volumes as demand accelerates for optical connectivity solutions powering next-generation AI training and inference infrastructure.

Contact: Chris Jost, 408-859-2995, cjost@aehr.com, www.aehr.com

Aerotech

Booth 5207
Release Date: 03/05/2026
Category: Manufacturing/Automation/Packaging Equip. & Materials

At OFC 2026 booth # 5707, Aerotech will demonstrate the revolutionary PICAlignTM multichannel active alignment architecture designed for high-volume Co-Packaged Optics (CPO) production. A collaborative effort between Aerotech, Santec and SENKO, this novel active alignment system integrates high-speed motion control, synchronized data acquisition and sophisticated alignment algorithms. The revolutionary PICAlignTM solution performs precise, rapid active alignments of multichannel arrays in six degrees of freedom, enhancing test and assembly processes for next-generation photonics and co-packaged optics technologies.

Contact: Amy McGrath, 267-337-2495, amcgrath@aerotech.com, www.aerotech.com

Applied Optoelectronics, Inc. (AOI)

Booth 739
Release Date: 03/02/2026
Category: Optical Transmitters/Receivers

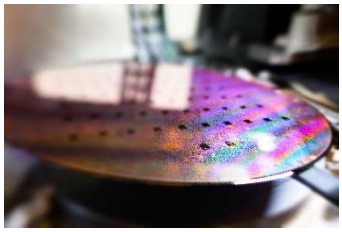
AOI will demonstrate its readiness for the industry's shift to CPO and NPO architectures, showcasing its full transceiver portfolio from 100G/400G/800G to 1.6T, along with live demos of its 6.4T on-board optics (OBO) and new 400-mW narrow linewidth pump laser for silicon photonics. With a new Texas manufacturing facility set for completion in late 2026, AOI is on track to become the largest U.S. producer of 800G transceivers. Its high-precision automated production and in-house laser chip fabrication help customers avoid geopolitical risks and supply chain delays, reducing dependencies on overseas logistics.

Contact: Sara Cicero, 770-331-0269, sara_cicero@ao-inc.com, www.ao-inc.com

CEA-Leti

Booth 5320
Release Date: 03/02/2026
Category: Integrated Photonics

CEA-Leti, leading European microelectronics research institute, and NcodiN, a deep tech startup specializing in nanolaser enabled photonic interconnects, will announce on March 11 a strategic collaboration to industrialize NcodiN's optical interposer technology on a 300 mm integrated photonics process. NcodiN, which received €16 million in seed financing last November, is developing optical interconnects designed to relieve a critical data-movement bottleneck limiting performance in next-generation semiconductors. The collaboration will accelerate the company's proof-of-concept work into industrial-grade 300 mm processes—moving beyond copper interconnects and marking a major step toward scalable, in-package, long-reach optical links for future computing architectures and artificial intelligence (AI) chips.



Contact: Sarah-Lyle Dampoux, +33 6 21 36 78 56, sldampoux@mahoneylyle.com, www.leti-cea.com

Chilas Lasers

Booth 957
Release Date: 03/02/2026
Category: Lasers - Communications

We're presenting our O-band narrow-linewidth, widely tunable laser at OFC 2026! ATLAS1310, scheduled for commercialization in Q2 this year, is an ultra-compact laser (about the size of a deck of cards), fully integrated with no moving parts, and capable of switching between wavelengths within 20 ms. Like the other lasers in ATLAS series manufactured by Chilas, it features wide tunability, ultra-narrow linewidth, fast wavelength modulation, and fiber-coupled output. Chilas will showcase a live demo of the O-band tunable laser at booth 957 (NL Pavilion, South Hall). Get in touch to learn more or schedule a meeting!

Contact: i.mateiciuc@chilasbv.com, +31854019151, www.chilasbv.com

DiCon Fiberoptics, Inc.

Booth 1353
Release Date: 03/02/2026
Category: Optical Components – Passive

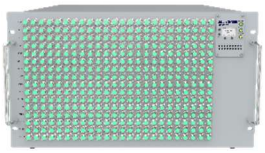
DiCon Fiberoptics, Inc. introduces its Space-Ready MEMS 1xN Optical Switches, having successfully passed the rigorous Space Radiation Effect Test. Building on years of LEO (Low Earth Orbit) satellite deployment with its Space-Grade MEMS Variable Optical Attenuators (VOA), this MEMS 1xN qualification reaffirms DiCon's commitment to high-reliability space-grade components. DiCon's products and its MEMS technology continue to set the standard for operating in extreme environments. Also in the pipeline, DiCon is evaluating the design for a space-grade matrix switch, further expanding its portfolio for satellite communications and aerospace applications. For more information about space-grade components, please contact DiCon.

Contact: Judy Chu, 510-620-5000, jchu@diconfiberoptics.com, www.diconfiberoptics.com

DiCon Fiberoptics, Inc.

Booth 1353
Release Date: 03/02/2026
Category: Laboratory & Test Equipment

DiCon Fiberoptics, Inc. introduces the MEMS 384 Anyport-to-Anyport Matrix Switch, designed to streamline high-volume testing for transceivers and Co-packaged Optics (CPO). Leveraging DiCon's field-proven MEMS platform, the switch offers unrivaled flexibility, allowing configurations from a symmetric 192x192 to an asymmetric 1x383 setup. Built on technology refined since 1998, this solution provides the stability and reliability required for rigorous automated test environments. The MEMS 384 ensures seamless scalability for the next generation photonic devices test setups.



Contact: Judy Chu, 510-620-5000, jchu@diconfiberoptics.com, www.diconfiberoptics.com

DiCon Fiberoptics, Inc.

Booth 1353
Release Date: 03/02/2026
Category: Optical Amplifiers

DiCon Fiberoptics Unveils Ultra-Compact Waveguide Optical Amplifier (WOA) After a decade of R&D, DiCon Fiberoptics introduces the Waveguide Optical Amplifier (WOA), a disruptive alternative to traditional EDFAs. This hermetically sealed device delivers >25 dB gain with significantly lower ASE noise than existing amplifiers. Featuring an in-house fabricated waveguide and micro optics, the WOA is designed for high-volume applications like optical communications and AI data centers, and specialty applications like Quantum computing and free space laser/RF systems. Its ultra-compact form factor and external control circuit enable rapid integration, setting a new benchmark for photonic reliability and performance.

Contact: Judy Chu, 510-620-5000, jchu@diconfiberoptics.com, www.diconfiberoptics.com

DiCon Fiberoptics, Inc.

Booth 1353
Release Date: 03/02/2026
Category: Data Center Inter Connects

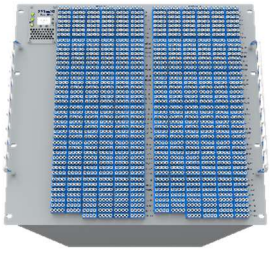
DiCon Fiberoptics unveils cost-effective MEMS Optical Circuit Switches (OCS) for AI data centers. Two new models are introduced: 300x300 and 64x64, optimized for leaf-and-spine and Torus AI architectures. These models deliver reliable, field-proven performance at a competitive price point. Building on a legacy of MEMS innovation since 2013, DiCon leads the market in shipping the largest All Optical Matrix Switch in the market, a 600x600 switch. The company is scaling its matrix switch production quickly to meet the rapidly growing market demands. DiCon expects to deliver > 2,000 units of matrix switches of various sizes this year.

Contact: Judy Chu, 510-620-5000, jchu@diconfiberoptics.com, www.diconfiberoptics.com

DiCon Fiberoptics, Inc.

Booth 1353
Release Date: 03/02/2026
Category: Switches, Routers and ROADMs

DiCon Fiberoptics announces breakthrough in MEMS 1024x1024 All Optical Matrix Switch. Following the successful launch of its 600x600 model, DiCon Fiberoptics is now prototyping the industry-leading MEMS 1024x1024 All-Optical Matrix Switch. Designed for AI Data Centers, Quantum Computing, Cybersurveillance, and Photonics Device Test Automation, this massive-scale switch will again showcase DiCon's hallmark reliability and superior MEMS product performance, with a target loss spec of < 3.0 dB. DiCon continues to push the boundaries of optical density to meet what the market demands. This milestone reinforces DiCon's leadership in MEMS based high-port-count all optical switching solutions.



Contact: Judy Chu, 510-620-5000, jchu@diconfiberoptics.com, www.diconfiberoptics.com

Epiphany Design

Booth 957
Release Date: 03/02/2026
Category: Integrated Photonics

Epiphany Design, a photonic design house from the Netherlands, will present at OFC 2026 its new Hybrid Laser Design Module: a ready-to-integrate, platform-agnostic laser building block for photonic integrated circuits. Instead of developing a hybrid laser from scratch, customers can integrate a validated laser architecture directly into their PIC layout, significantly reducing time-to-market, complexity, and technical risk. Epiphany will also showcase a fully assembled laser demonstration unit, available to customers for in-house evaluation and lab testing prior to full integration.

Contact: +31 53 2065007, i.mateiciuc@epiphany-design.com, www.epiphany-design.com

Ethernet Alliance

Booth 5023
Release Date: 02/25/2026
Category: High Speed Technology and Data Formats

The Ethernet Alliance interoperability demonstration at OFC 2026 will focus on high-speed Ethernet technologies designed for AI-driven and data-intensive environments. Building on recent industry progress, it will explore advanced signaling, optics, and system architectures capable of supporting bandwidth growth from 100G, to 800G, and toward 1.6T and beyond. There will be solutions from a wide range of ecosystem participants, including test & measurement, interconnect, systems, and switches. The interoperability demos offer attendees a chance to see state-of-the-art networking technologies operating in a real-world setting.

Contact: Laurie Davis, 804-337-2569, laurie_davis@interprosepr.com, www.ethernetalliance.org

FIBERSTAMP TECHNOLOGY

Booth 2416
Release Date: 02/28/2026
Category: Optical Transmitters/Receivers

FIBERSTAMP's 800G OSFP HYBRID ACC+ and 800G OSFP HYBRID VR8-AOC, recognized as 2026 Lightwave Innovation Reviews Honorees, will be showcased live at OFC 2026, Booth #2416. These next-generation hybrid interconnect solutions are engineered for AI and hyperscale data center environments, delivering optimized performance with lower power consumption and reduced latency. The VR8-AOC enables high-performance optical connectivity for extended reach, while the ACC+ provides a power-efficient active copper solution for short-reach applications. Visit Booth #2416 for live demos and experience how FIBERSTAMP is advancing 800G connectivity for next-gen network infrastructure.

Contact: FIBERSTAMP TECHNOLOGY, kettykang@fiberstamp.com, www.fiberstamp.com

G&H (Gooch & Housego)

Booth 1022
Release Date: 03/04/2026
Category: Optical Components - Active/Dynamic

G&H is expanding U.S. production of Thin-Film Lithium Niobate (TFLN), a key technology for next-generation optical communications. TFLN enables high bandwidth, low loss, and improved power efficiency for advanced modulation and photonic integrated circuits. By becoming the leading U.S.-based TFLN manufacturer, G&H aims to strengthen domestic supply chains for commercial and high-reliability communications. This expansion complements its existing fiber optic portfolio, reinforcing its vertically integrated capabilities across passive and active photonic technologies for future optical transport systems. G&H experts will be available at OFC 2026 to discuss fiber solutions, smart sensing, TFLN manufacturing, and custom photonic designs.

Contact: Laura Beasley, +44 (0)7714641879, lbeasley@gandh.com, www.gandh.com

La Luce Cristallina

Booth 5507
Release Date: 02/24/2026
Category: Integrated Photonics

On March 10th, La Luce Cristallina announced the beta availability of its 200-mm (8-inch) barium titanate ($BaTiO_3$) wafer, now open to customers for evaluation. Designed for advanced electro-optic modulators in telecom and datacom, the CMOS-compatible platform supports co-packaged optics architectures targeting next-generation AI infrastructure. The material's high Pockels coefficient enables ultra-low-voltage operation while allowing clean integration into existing silicon manufacturing processes without fab retooling. Beyond optical interconnects, the company is positioning $BaTiO_3$ for LiDAR, biomedical sensing and quantum computing applications. La Luce Cristallina will showcase its wafer portfolio at OFC 2026 in Los Angeles.

Contact: Jeannette Bitz, 510-295-4972, laluce@engagepr.com, www.lalucecristallina.com

LightSpeed Photonics

Booth 4475
Release Date: 03/05/2026
Category: Data Center Inter Connects

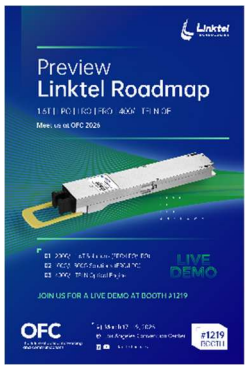
LightSpeed Photonics launches Industry's First "Solderable" Near Packaged Optical Interconnect Technology. Lightspeed Photonics has the world's first solderable VCSEL-based optical interconnects that are compact, low power, and can be kept near the ASICs. The new "NPO" is positioned as the "Goldilocks" solution between CPO and LPO with less power, featuring tiny footprint, soldered near-chip enable faster data processing. LightSpeed Photonics CEO, Rohin Y, to speak on the topic of near-packaged optics on March 19 at OFC Conference.

Contact: Frank Buscemi, 248-856-8636, fbuscemi@mbe.group, www.lightspeedphotonics.com

Linktel Technologies

Booth 1219
Release Date: 03/05/2026
Category: Data Center Inter Connects

Linktel Technologies to Showcase Next-Gen 1.6T Solutions and TFLN Optical Engine at OFC 2026 Linktel



Technologies (Booth #1219) invites attendees to experience the future of optical networking with live demonstrations of its latest roadmap: 200G/L 1.6T Solutions: Featuring FRO, LRO, and LPO configurations. 100G/L 800G Solutions: Showcasing high-performance FRO and LPO modules. 400G/L TFLN Optical Engine: Highlighting cutting-edge TFLN technology. Visit us at the Los Angeles Convention Center, March 17-19, to explore our comprehensive high-speed connectivity portfolio.

Contact: sherry@linktel.com, +8615827611228, www.linktel.com

Linque

Booth 520
Release Date: 03/02/2026
Category: Integrated Photonics

Linque will unveil at OFC 2026 its new 64-port all-optical circuit switch RISE64, engineered to deliver ultra-low latency, high-bandwidth connectivity for hyperscale and AI-driven data center environments. Leveraging its unique low-loss programmable silicon photonic chip technology, the platform enables dynamic, circuit data routing without optical-electrical-optical (OEO) conversion, significantly reducing power consumption and operational complexity. The 64-port architecture supports scalable spine-leaf topologies, providing deterministic performance for high-performance computing and AI workloads. The system is available to selected customers for evaluations.

Contact: Samarth Vadia, +49 17 63 43 78124, marketing@linque.eu, www.linque.eu

NLM Photonics

Meeting Room 5544
Release Date: 03/04/2026
Category: Polymer Optics

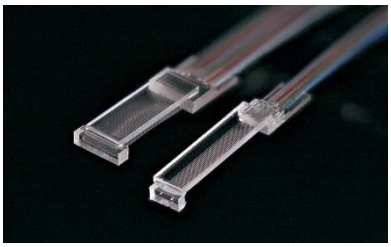
NLM Photonics Initiates Sampling of 1.6T and 3.2T Silicon Organic Hybrid PICs. The live demonstration at OFC features a 1.6T DR8 PIC built with NLM's patented Selerion™-HTX, an organic material, achieving an order-of-magnitude better performance than traditional silicon photonics. The 1.6T and 3.2T PICs were fabricated on Advanced Micro Foundry's (AMF) 200 mm GP O-band silicon photonics platform. NLM's 1.6T SOH PIC is 40 percent smaller than standard 1.6T silicon photonic PICs, delivering 200Gb/s per lane bandwidth with lower drive voltage and higher extinction ratios. The 3.2T PIC delivers 110+ GHz performance in the same form factor. Building on record-setting demonstrations of 1.6T and 3.2T in 2025, NLM is meeting with customers and ecosystem partners to share their latest test results and plans for 2026 and beyond.

Contact: Theo McGillivray, 206-235-4933, press-relations@nlmphotonics.com, www.nlmphotonics.com

MicroAlign

Booth 859
Release Date: 02/25/2026
Category: Fiber Manufacturing Equipment

MicroAlign has been awarded a €2.5 million EIC Accelerator Grant to accelerate the industrialization of its fiber-array manufacturing. The company's patented active-alignment micro-manipulation technology enables nanometer-level positioning accuracy, delivering scalable, ultra-low-loss fiber-to-chip connectivity for photonic quantum computing and advanced photonics applications. MicroAlign is advancing the next generation of ultra-high-accuracy fiber arrays featuring channel pitches down to 127 µm, supporting high-density optical interconnects for photonic quantum computing and beyond.



Contact: MicroAlign, 631-740-4558, e.kazakova@microalign.nl, www.microalign.nl

Nicslab Ops, Inc.

Booth 4565
Release Date: 03/02/2026
Category: Production Test Equipment

As a fabless semiconductor company addressing the electronic bottleneck in Photonic Integrated Circuits (PICs), Nicslab develops highly integrated mixed-signal platforms used by distinguished research

labs, and leading universities. At OFC 2026, the company will highlight its Mini-ATE compact tester, XDAC programmable multichannel SMU, and XSOM modular system-on-module—solutions engineered for precise timing, synchronized digital–analog control, and scalable photonic system integration. Nicslab continues to advance electronic–photonic convergence for AI, quantum research, and next-generation sensing applications.

Contact: Muhamad Rizal Abdullah, +62 856-2419-2118, rizal@nicslab.com, www.nicslab.com

OEwaves, Inc.

Booth 350
Release Date: 02/25/2026
Category: Laboratory & Test Equipment

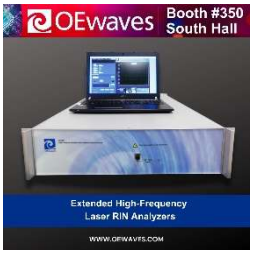
40 GHz Laser Phase Noise Measurement Option OEwaves, Inc. announced a 40 GHz extended-frequency option for its HI-Q® OE4000 Laser Linewidth and Phase Noise Analyzer. The upgrade enables absolute phase and frequency noise measurements from 1 Hz to 40 GHz, enhancing ultra-high offset characterization and next-generation laser research and development capabilities.

Contact: Orri Jonsson, 970-232-6864, orri.jonsson@oewaves.com, www.oewaves.com

OEwaves, Inc.

Booth 350
Release Date: 02/25/2026
Category: Laboratory & Test Equipment

Extended High-Frequency Laser RIN Analyzers. OEwaves, Inc. expanded its HI-Q® OE4001 Relative Intensity Noise Analyzer with high-frequency RIN solutions up to 110 GHz and beyond. Featuring modular configurations, ultra-low noise floor, intuitive PC control, and remote operation, the system enables flexible, cost-effective, high-performance laser noise measurements.



Contact: Orri Jonsson, 970-232-6864, orri.jonsson@oewaves.com, www.oewaves.com

OIF

Booth 2017
Release Date: 02/24/2026
Category: Communications Equipment

OIF will bring interoperability to life at OFC 2026 (March 17–19, Los Angeles), with 40 member companies demonstrating the multi-vendor building blocks AI-era data center networks depend on. At booth #2017, OIF's interoperability showcase turns Implementation Agreements into working, repeatable interoperability so operators can reduce integration risk, maintain sourcing flexibility and move from innovation to deployment with greater confidence. Live demos span coherent interoperability (400ZR, 800ZR, multi-span, MCF and controllers), high-speed electrical interfaces (CEI-224G and a live 448G demo), CMIS management advances and energy-efficient interfaces plus co-packaging. OIF experts will also lead three show floor theater panels.

Contact: Leah Wilkinson, 703-307-3964, leah@wilksinon.associates, www.oiforum.com/

OpenLight Photonics

Booth 2449
Release Date: 03/05/2026
Category: Integrated Photonics

OpenLight announced the first-ever volume production orders by a customer on its PH18DA indium phosphide (InP) on silicon photonic platform, developed in collaboration with Tower Semiconductor. This milestone based on NewPhotonics® 800G and 1.6T laser-integrated PIC solution marks a major step forward bringing highly integrated, laser-enabled photonic ICs into high-volume production for AI and hyperscale data center networks. For OpenLight, this production order represents an important transition from advanced development to manufacturing-ready deployment, validating the PH18DA process as a scalable, production-proven platform for next-generation optical connectivity. NewPhotonics is the first OpenLight customer to bring its designs to volume production on PH18DA, enabling improved bandwidth density, power efficiency, and footprint reduction compared with conventional discrete silicon photonics optical implementations.

Contact: Natalija Filipovic, 613-299-8339, nfilipovic@openlightphotonics.com, www.openlightphotonics.com

Optiwave Systems Inc.

Booth 924
Release Date: 02/20/2026
Category: Software

FEMFy is a frequency domain solver designed to streamline the simulation of integrated photonic devices. By automating the workflow from layout to analysis, it seamlessly integrates with popular Python libraries like gdstk to generate meshes directly from GDS files and function-defined structures. It supports importing GDSII files from GDSFactory and K-layout. FEMFy eliminates manual setup with auto-port detection and rigorously models irregular geometries using flexible first- and second-order elements. Featuring Perfectly Matched Layers (PML) for boundary truncation, the tool supports 2D and 2.5D simulations for TE and TM polarizations, offering a rapid, high-fidelity alternative to computationally expensive 3D solvers.

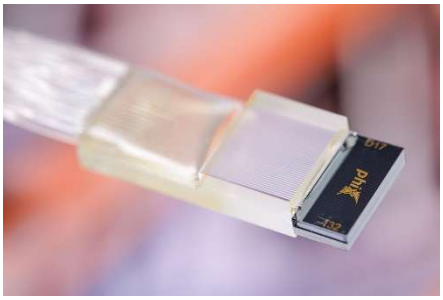
OptiOmega
Photonics Device and Circuit Design Software Package

Contact: Sawyer Ge, 613-415-0261, sawyer.ge@optiwave.com, www.optiwave.com

PHIX Photonics Assembly

Booth 754
Release Date: 02/23/2026
Category: Integrated Photonics

PHIX is introducing a new variation of silicon nitride spot size converters (SSCs)! This complements our existing offering of this highly scalable multi-channel solution for mode field conversion between fiber arrays and PICs. The new SSCs are suitable for PICs of up to 16 or 32 optical channels and operate in the C-band or O-band. Some convert to circular (approx. 1.5 - 3 µm) mode fields, while others convert to elliptical (approx. 3 x 1 µm) mode fields and feature angled waveguides specifically tailored to indium phosphide PICs.



Contact: Gijs van Ouwerkerk, +31 88 7449 009, g.vanouwerkerk@phix.com, www.phix.com

PHOGRAIN

Booth 1413
Release Date: 02/26/2026
Category: Optical Transmitters/Receivers

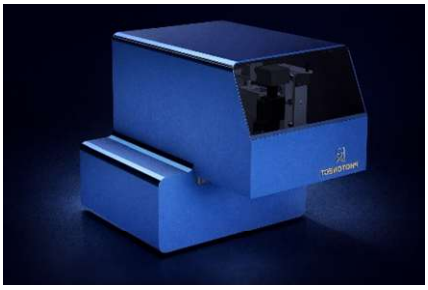
As a leader in photodetector chips and intelligent sensors, PHOGRAIN owns hundreds of patents with hundreds of millions of units shipped. Adopting an IDM model, it provides customers with integrated one-stop solutions.

Contact: ge_liu@PHOGRAIN.com, +86 181-886-11190, ge_liu@PHOGRAIN.com, www.PHOGRAIN.com

Photonect Interconnect Solutions Inc.

Booth 5048
Release Date: 02/19/2026
Category: Manufacturing/Automation/Packaging Equip. & Materials

Photonect will launch PIX-Attach™, a first-of-its-kind semi-automated laser splicing fiber-attach machine designed to eliminate epoxy in fiber-to-photonic chip attachment. Addressing a major scalability bottleneck in photonic packaging, PIX-Attach replaces manual, labor-intensive alignment processes with an integrated optical alignment and laser fusion system. The modular platform enables up to 60 units per hour, supporting both pilot lines and volume manufacturing. It delivers low-loss, mechanically robust, and repeatable optical interconnects while reducing dependency on specialized labor. This system can also retrofit into existing machinery to accelerate scalable photonic production. Photonect will showcase the platform and discuss early access opportunities at OFC, Booth #5048.



Contact: Deshna Pancholi, 574-208-7494, deshna@photonectcorp.com, www.photonectcorp.com/

PhotonIC Technologies

Booth 5616
Release Date: 02/27/2026
Category: Optical Components - Active/Dynamic

PhotonIC Technologies debuts its Resiliency of Optoelectronic Chip Supply-Chain™ (ROCS) platform, introducing a complete optoelectronic IC portfolio spanning 10G to 1.6T. ROCS enables true design portability across CMOS and SiGe processes and multi-country fabs, giving engineers greater control over performance, power, cost, and long-term sourcing strategy. With more than 70 patents and over 40 million ICs shipped worldwide, PhotonIC supports Tier-1 customers across datacenter, 5G, sensing, and automotive markets. Built on mature, high-yield nodes and qualified across multiple fabs, ROCS delivers scalable bandwidth with predictable performance and resilient global manufacturing.

Contact: Linda Ferguson, 503-869-5827, linda@lcfmarketing.com, www.photonic-tech.com

Quantum Computing Inc.

Booth 5355
Release Date: 03/10/2026
Category: Communications Equipment

Quantum Computing Inc. and Ciena will showcase a live demonstration of next-generation quantum-secure communications at OFC 2026 in the Corporate Village (Booth #5355). The demonstration highlights a comprehensive security architecture using quantum key distribution (QKD) and classical authentication methods leveraging AES-256-GCM optical encryption scaling up to 1.6Tb/s. Combining QCi's time-frequency entanglement-based QKD and previewing quantum identity authentication (QIA) technologies with Ciena's Waveserver wire-speed encryption platform that uses NIST-certified PQC algorithms, this solution demonstrates how network operators can protect critical in-flight data across while preparing for future cybersecurity threats posed by quantum computing. Please schedule your demonstration appointment.

Contact: Karen Jeffers, kjeffers@quantumcomputinginc.com, 609-285-3496, www.quantumcomputinginc.com

SANWA Technologies, Inc.

Booth 1017
Release Date: 03/04/2026
Category: Fiber Cables, Assemblies

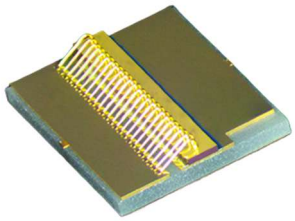
US Conec, Hakusan, and Sanwa Technologies Announce Agreements to Multi-Source and Develop MMC Very Small Form Factor (VSFF) Connector and TMT Ferrule Solutions

Contact: runa.saga@snwtech.com, 972-685-1980, www.sanwa-tech.com

SemiNex Corporation

Booth 2348
Release Date: 03/05/2026
Category: Optical Amplifiers

SemiNex Corporation, a U.S. leader in high-power semiconductor lasers and optical amplifiers, announces Ultra-High Power O-band SOA that can achieve 30dBm (1 Watt) output power with over 25% PCE at 50°C. This exciting technology can enable high data rate required in co-packaged optics (CPO) for next-generation Data Center and optical interconnects for AI and high-performance computing. The Ultra-High-Power SOA is built on SemiNex' advanced and proprietary epitaxy and optical waveguide structures featuring high reliability and performance. Our experienced team can support partners to integrate the Ultra high-power SOA with Silicon PICs for ELSFP or CPO used in Data Centers.



Contact: Daniel Chu, 978-430-0425, dchu@seminex.com, www.seminex.com

Semtech

Booth 1812
Release Date: 03/02/2026
Category: Data Center Inter Connects

As AI data centers race to scale bandwidth while containing power consumption, the industry is rapidly moving beyond DSP-based optical architectures toward linear interconnects. For OFC, Semtech will unveil a family of 224G per lane TIAs and MZM drivers purpose-built for this transition – enabling 800G, 1.6T and 3.2T transceivers and optical engines across LRO, LPO, XPO, NPO and Co-Packaged Optics (CPO) applications. The new devices are designed to give module and system designers a single, cohesive solution for the full range of linear optics architectures for AI/ML clusters, hyperscale data centers and next-generation cloud infrastructure.

Contact: Sel Tafolla, 805-908-6168, stafolla@semtech.com, www.semtech.com

Shanghai Beeplux Semiconductor Technologies

Booth 4872
Release Date: 02/26/2026
Category: Optical Comm. & Transport Sub-systems

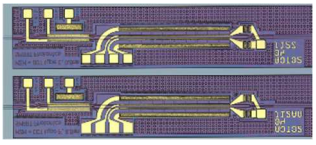
Beeplux Semiconductor is unveiling its latest high-performance silicon photonics optical engines, specifically engineered for the rigorous demands of next-generation AI data centers. These monolithically integrated transmitter chips support 100Gbps and 200Gbps per lane architectures, providing a scalable path for 400G (DR4) and 800G (DR8) configurations. Optimized for Linear Pluggable Optics (LPO) applications, the design prioritizes high electro-optic bandwidth (exceeding 54 GHz for 100G lanes and reaching 63 GHz for 200G lanes) and low optical insertion loss to enable ultra-low-power, high-bandwidth interconnects with simplified system architectures. High-Efficiency 8x8 Optical Circuit Switch (OCS) Addressing the need for agile and reliable network management, Beeplux introduces its 8x8 Optical Circuit Switch (OCS) designed for large-scale AI infrastructure. This product features a non-blocking architecture and a hot-swappable design, ensuring seamless integration and high availability in mission-critical environments. With a focus on efficiency and performance, the OCS offers low on-chip insertion loss (2 dB), fast switching speed (ms level), and polarization-insensitive operation, making it an ideal solution for temperature-insensitive optical switching across eight channels.

Contact: David Zheng, 626-710-2341, david.zheng@beepluxsemi.com, www.beepluxsemi.com

SMART Photonics

Booth 855
Release Date: 03/02/2026
Category: Integrated Photonics

SMART Photonics releases new 110+ GHz modulator - for your 3.2T applications Our new 110+ GHz Indium Phosphide Mach-Zehnder Modulator delivers industry-leading performance for ultra-high-speed optical transmission. Supporting digital bandwidth above 110 GHz, it is ideally suited for 400G/lane PAM4 and enables the next generation of faster 3.2T data-center interconnect solutions.



Contact: Erik Luyk, +31651739344, erik.luyk@smartphotonics.nl, www.info.smartphotonics.nl

Stäubli

Booth 4557
Release Date: 02/12/2026
Category: Data Center Inter Connects

Stäubli is showcasing a major leap in thermal management as optical modules push toward 1.6 Tb/s and generate unprecedented heat. The new Mini QD connector brings liquid cooling directly to next-generation pluggable optical modules, removing thermal barriers that limit bandwidth and density. Stäubli and Ciena are also leading the Mini-QD standardization effort, while Stäubli also continues to contribute to the updated UQD v2 specification, strengthening reliability and interoperability across suppliers—positioning liquid cooling as the next essential step for high-performance optical systems.

Contact: Esther Hall, 864-316-9305, e.hall@staubli.com, www.staubli.com

Taara

Booth 4838
Release Date: 02/24/2026
Category: Communications Equipment

Taara has launched Lightbridge Pro, a carrier-grade wireless optical solution delivering 20 Gbps connectivity with 99.999% ("five nines") uptime. Built on its proven Lightbridge technology, it features intelligent, integrated switching to fiber or RF backup, enabling automatic hitless switchover during adverse weather — eliminating the delays common in traditional architectures. Designed for large operators and mission-critical networks, it supports mobile backhaul, urban densification, and data centre applications, with full FCAPS management and OSS/BSS integration. Already deployed in 20+ countries with operators like T-Mobile and Airtel, Taara will showcase Lightbridge Pro at MWC Barcelona 2026.

Contact: Ellie Joo, 650-276-9907, jiyeonj@taaraconnect.com, www.taaraconnect.com

Taara

Booth 4838
Release Date: 02/24/2026
Category: Communications Equipment

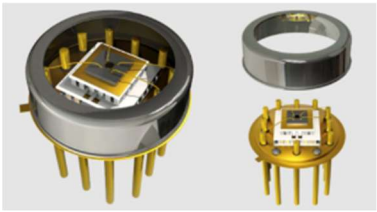
Taara has unveiled Taara Photonics, the world's first wireless communication platform built on optical phased arrays, alongside debut product Taara Beam. The platform replaces mechanical free-space optical beam-steering with solid-state photonic control, integrating over a thousand miniature light emitters into a single silicon photonics module the size of a finger. Taara Beam delivers up to 25 Gbps of low-latency optical connectivity across distances up to 10 kilometres in a shoebox-sized form factor, deployable in hours. By shifting beam tracking, shaping, and steering into an integrated photonic circuit, the system achieves greater precision than legacy mirror-based architectures.

Contact: Ellie Joo, 650-276-9907, jiyeonj@taaraconnect.com, www.taaraconnect.com

Tark Thermal Solutions

Booth 5012
Release Date: 02/25/2026
Category: Optical Components - Passive

Tark Thermal Solutions, formerly Laird Thermal Systems, has introduced its new two- and three-stage OptoTEC® MSX Series micro multistage thermoelectric coolers for infrared sensors and X-ray detectors. Designed for high coefficient of performance, the MSX Series achieves temperature differentials of 100–120°C in vacuum environments. With compact cold-side footprints as small as 2.0 x 4.0 mm and heights starting at 3.3 mm, these coolers deliver powerful performance in space-constrained designs. Built using advanced thermoelectric materials and high-temperature solders, they increase cooling capacity by up to 10%, reduce thermal noise, enhance imaging accuracy, and support reliable, maintenance-free operation in demanding optical and X-ray applications.



Contact: Allison Turner, 919-597-7335, allison.turner@tark-solutions.com, www.tark-solutions.com

Triple-Stone Technology Co., Ltd.

Booth 2339
Release Date: 03/05/2026
Category: Communications Equipment

Triple-Stone is a leading supplier of optical networking solutions. Our products include industry-leading OCS (Optical Circuit Switch), high-density connectivity products (MCF FIFO, shuffle box, FAU),we provide key devices for Erbium-Doped Fiber Amplifiers and a full range of Optical Active devices.

Contact: Lijun Guo**,** +86 13709686019**,** lijunguo@triple-stone.com, www.triple-stone.com

VIAVI Solutions

Booth 1239
Release Date: 03/02/2026
Category: Network Test Equipment

At OFC, VIAVI (NASDAQ: VIAV) will showcase advanced technologies for the validation of next-generation AI fabrics to give a comprehensive and AI-fabric-aware view of the network at scale. Demonstrations will focus on validation for 1.6T Ethernet, and PCIe® over optics, with VIAVI's ONE LabPro and TestCenter platforms for OSI L0-3 traffic generation and analysis being showcased alongside its recently announced hollow-core fiber test solution and DCX-700 optical loss 24-fiber test set. New product launches will include probe microscopes, high-density and a high-density OSFP test platform to validate1.6T Ethernet infrastructure. For further details and presentation locations/timings please visit https://go.viavisolutions.com/ofc-2025/p/1

VIAVI Solutions

Contact: Grand Bridges, 415-800-4529, emma@grandbridges.com, www.viavisolutions.com

VPIphotonics

Booth 431
Release Date: 02/11/2026
Category: Manufacturing/Automation/Training

VPIphotonics and NextCorps Luminate Launch New Collaboration to Empower Photonic Startups. VPIphotonics, a global leader in end-to-end photonic design automation software, announced today a new initiative aimed at supporting emerging photonics companies through a partnership with NextCorps

Luminate, the world's largest business accelerator for startups with optics, photonics, and imaging-enabled technologies. The partnership offers NextCorps and Luminate Accelerator early and growth stage companies access to advanced simulation tools, training resources, and certification pathways, strengthening their technical and commercial readiness. VPIphotonics' professional-grade software is used by industry-leading companies developing next-generation photonic integrated circuits, datacenter interconnects, quantum communications, laser satellite communications, and related technologies.

Contact: Chris Maloney, 585-705-9228, chris.maloney@vpiphotonics.com, www.vpiphotonics.com